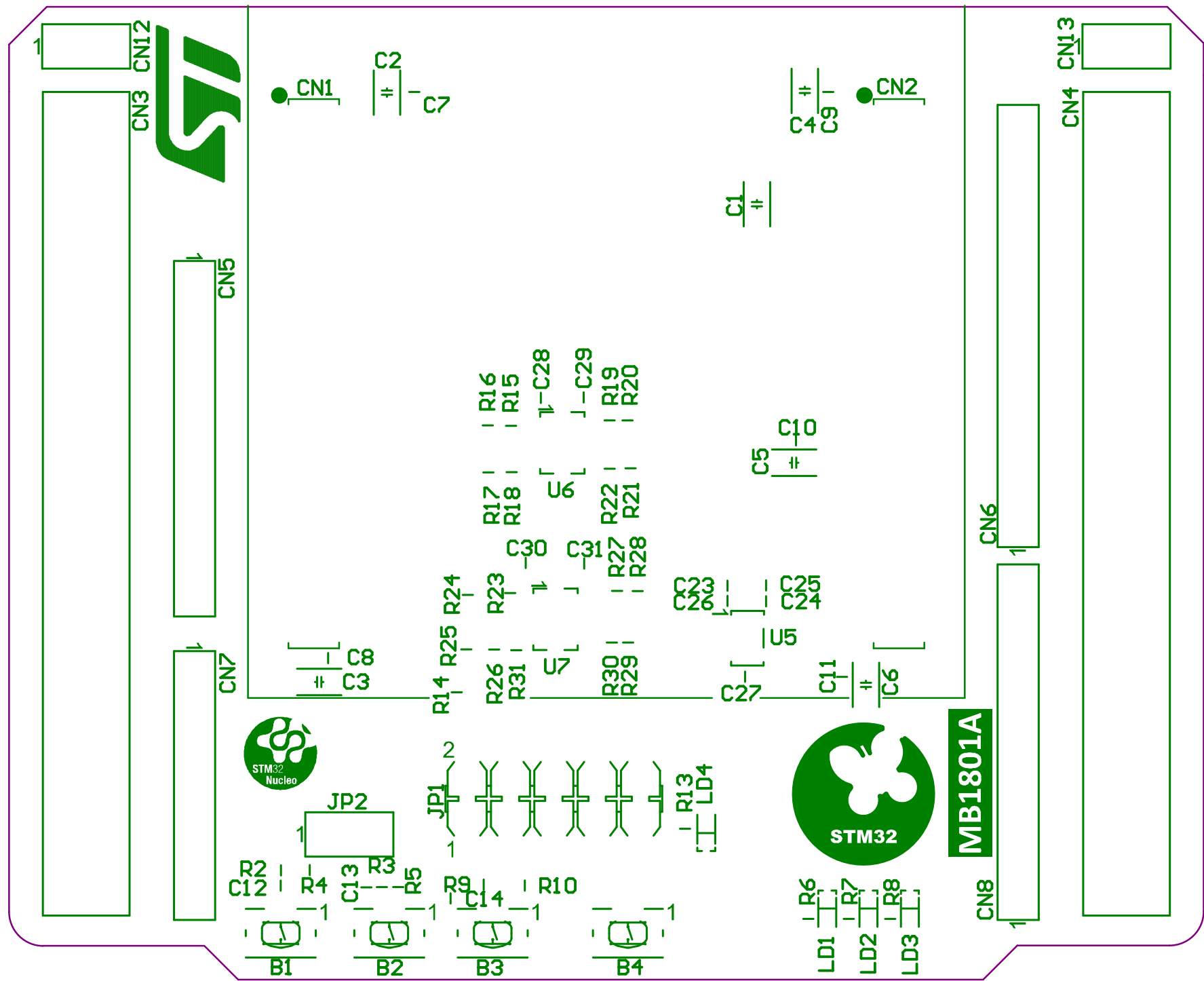
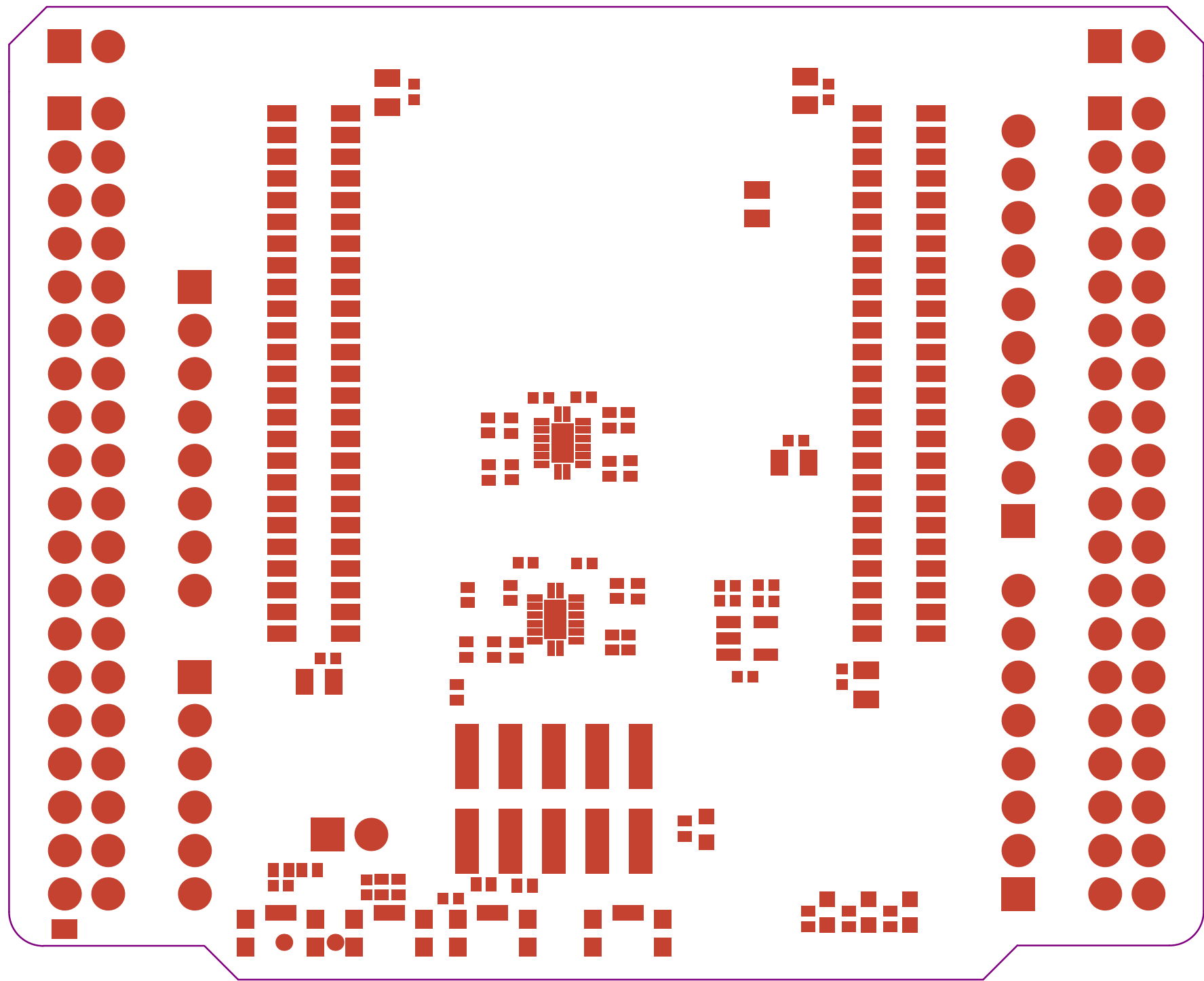


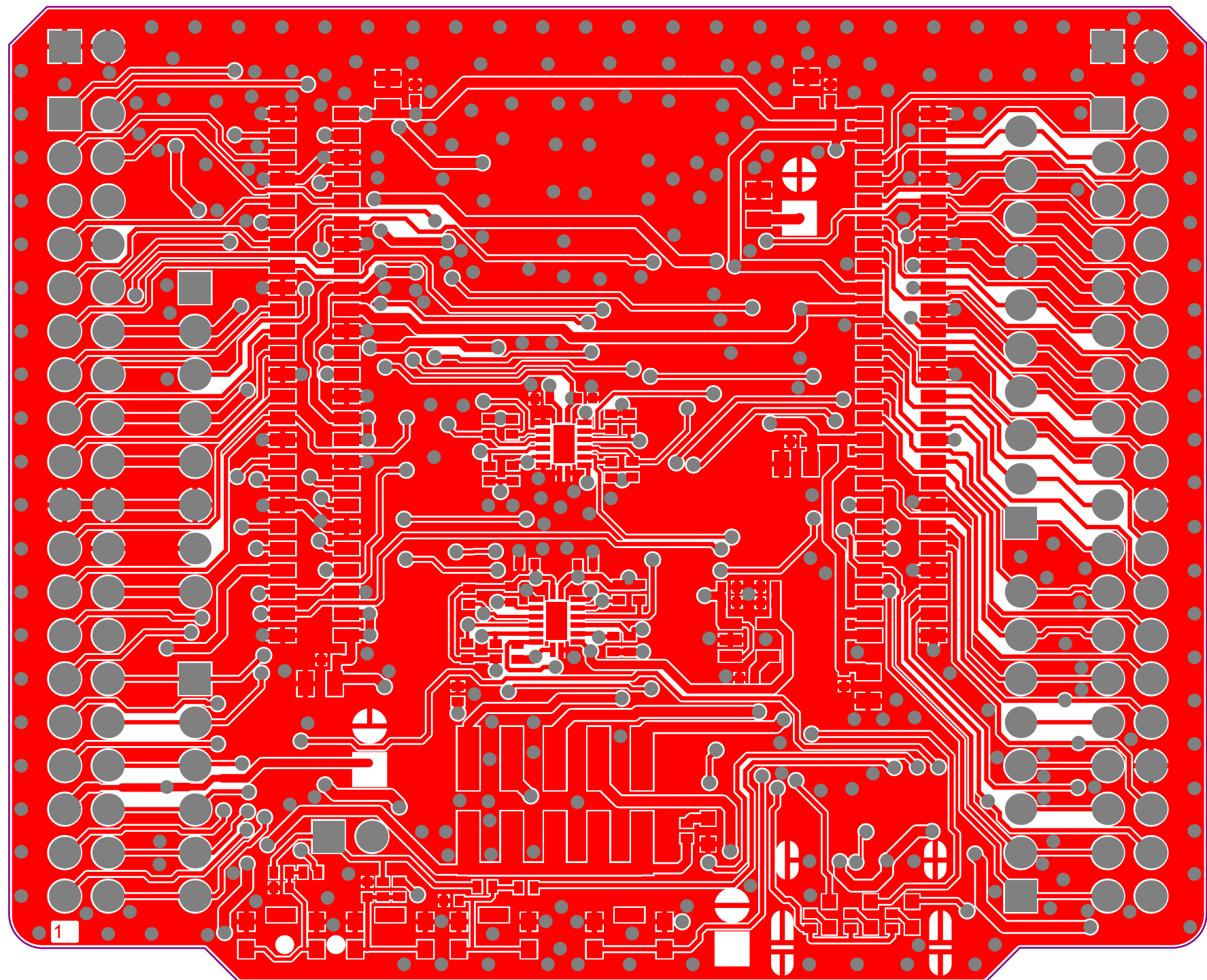
Project: NUCLEO64-MiniBoard		
Layer: Top Overlay	Gerber: .GTO	
Variant: NoUSB	Ref: MB1801	
Date: 17-OCT-2021	Rev: A	

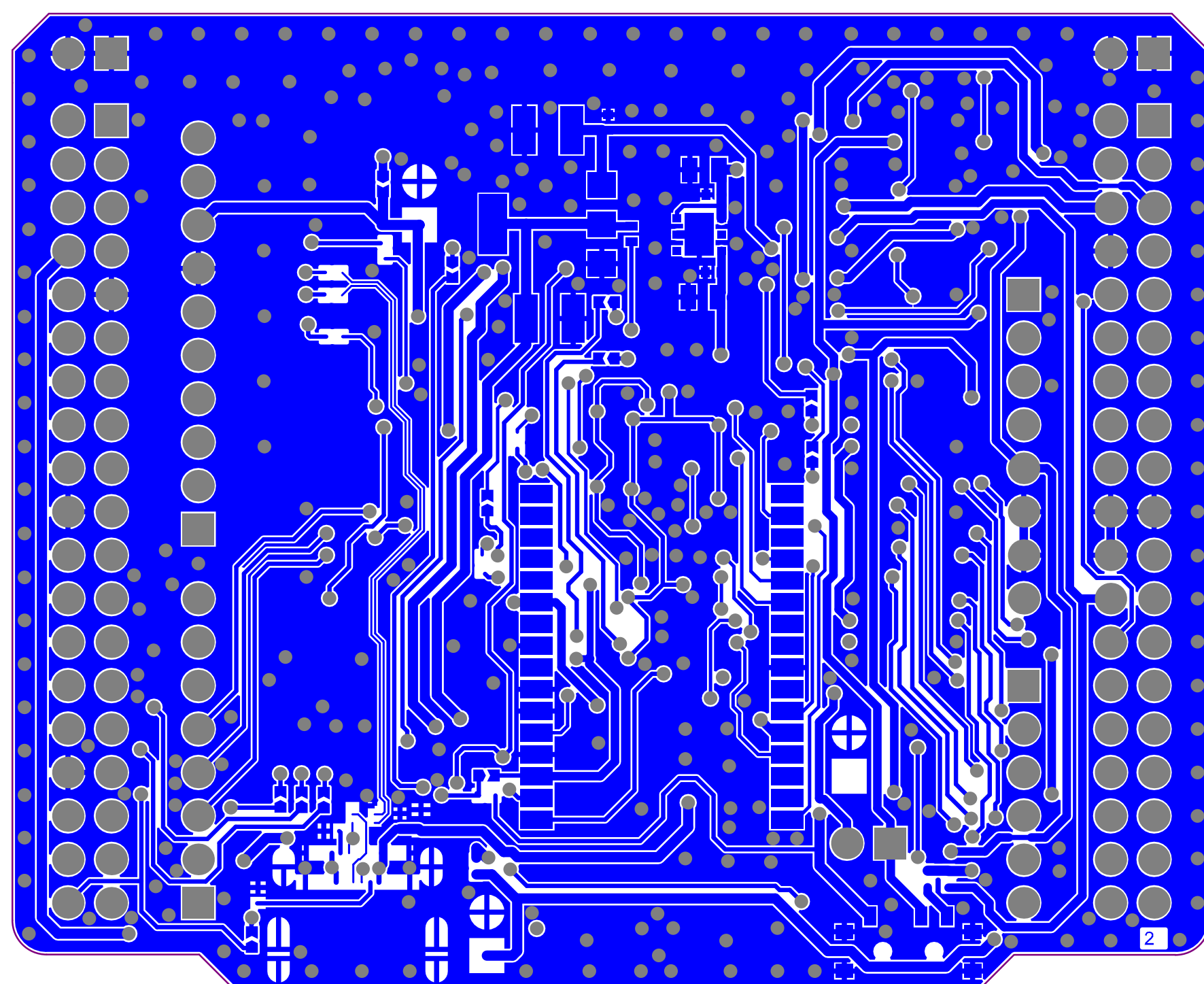


Project: NUCLEO64-MiniBoard		
Layer: Top Solder	Gerber: .GTS	
Variant: NoUSB	Ref: MB1801	
Date: 17-OCT-2021	Rev: A	

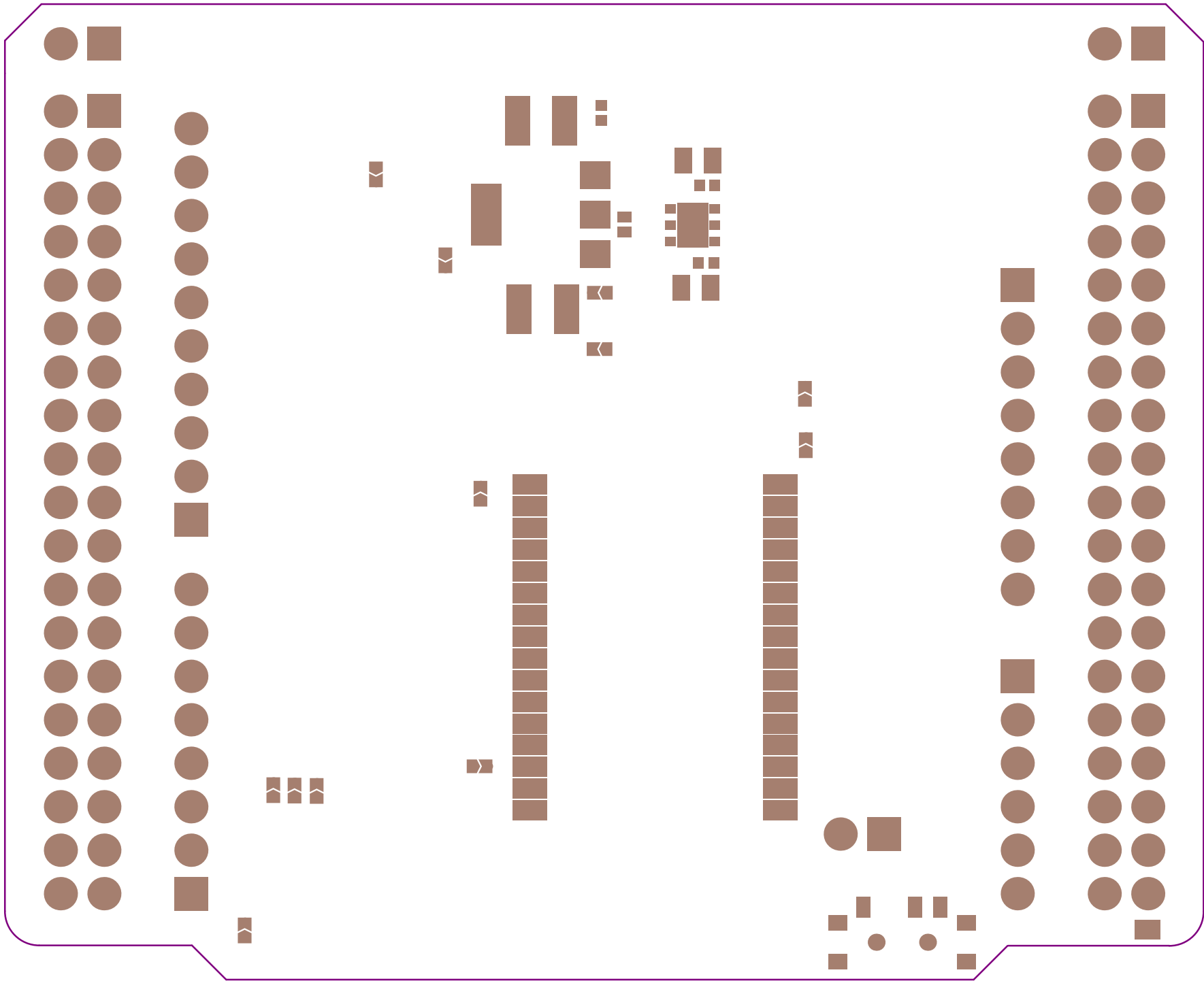


Project: NUCLEO64-MiniBoard		
Layer: Top Layer	Gerber: .GTL	
Variant: NoUSB	Ref: MB1801	
Date: 17-OCT-2021	Rev: A	





Project: NUCLEO64-MiniBoard		
Layer: Bottom Layer	Gerber:.GBL	
Variant: NoUSB	Ref: MB1801	
Date: 17-OCT-2021	Rev: A	



Project: NUCLEO64-MiniBoard

Layer: Bottom Solder

Variant: NoUSB

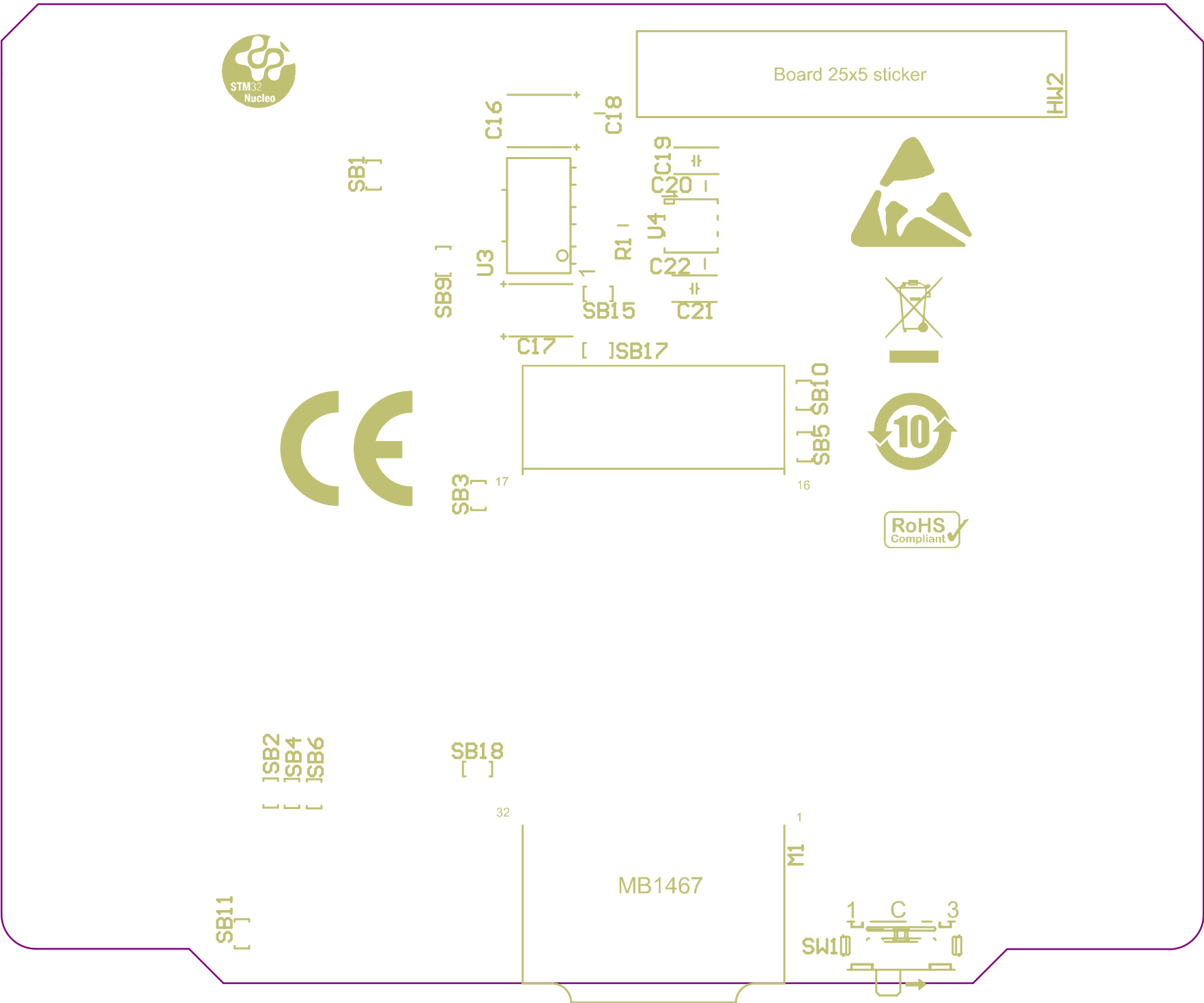
Date: 17-OCT-2021

Gerber:.GBS

Ref: MB1801

Rev: A





Project: NUCLEO64-MiniBoard

Layer: Bottom Overlay

Gerber:.GBO

Variant: NoUSB

Ref: MB1801

Date: 17-OCT-2021

Rev: A



PCB SPECIFICATIONS :

A. MATERIAL :

FR-4

☒ TG-170

☐ TG-150

☐ TG-140

B. MATERIAL FAMILY :

N/A

C. SOLDERMASK COLOR :

☐ GREEN

☒ WHITE

☐ RED

☐ BLACK

D. SILKSCREEN COLOR :

☒ BLUE

☐ YELLOW

☐ BLACK

E. SURFACE FINISH :

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

F. IMPEDANCE CONTROL :

☒ NO

☐ YES (SEE IMPEDANCE TABLE FOR DETAIL INFORMATION)

G. THROUGH VIA :

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.

PLUG MATERIAL : ☒ SOLDERMASK

☐ NON-CONDUCTIVE EPOXY.

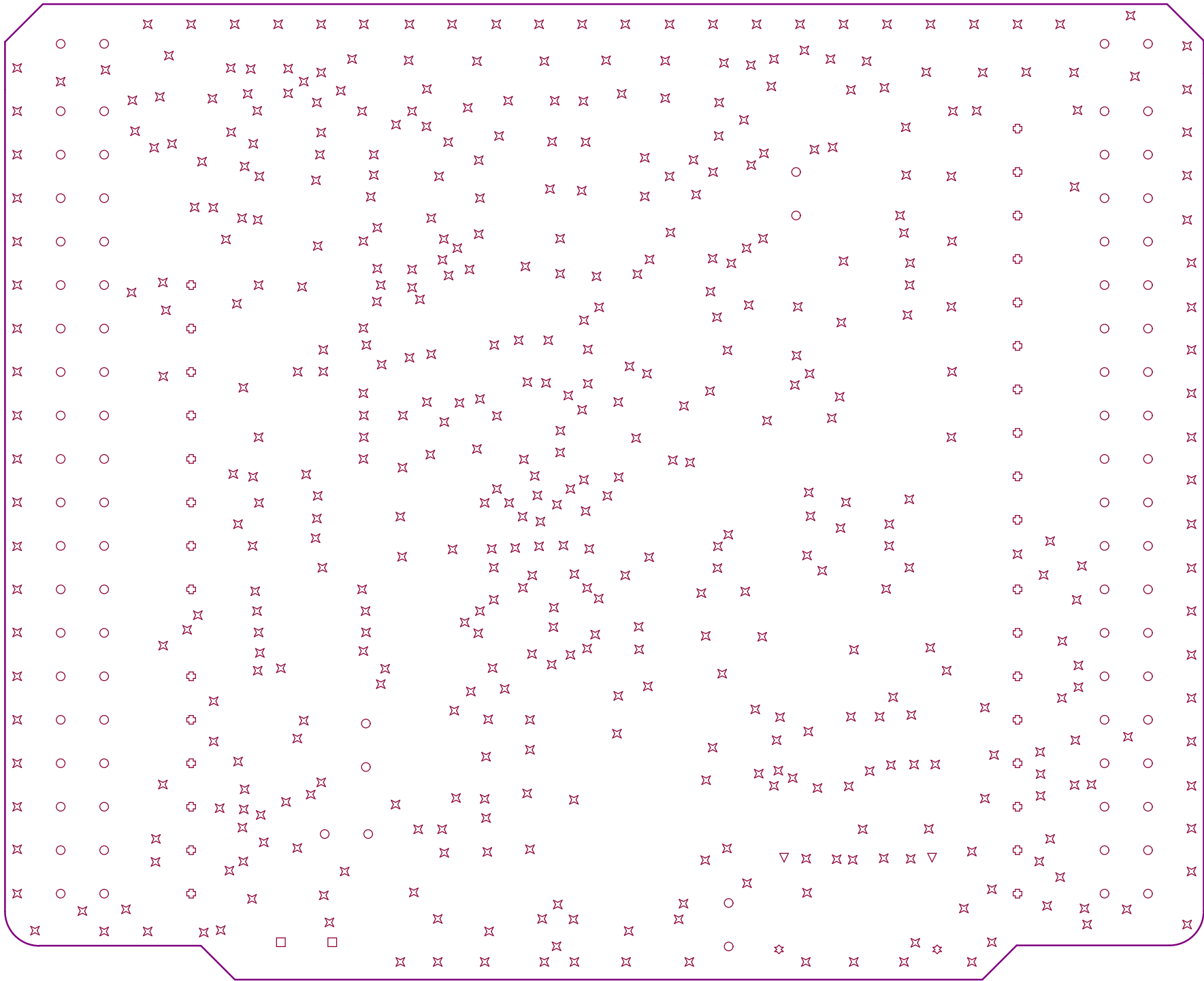
H. STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)	Hole Length	Routed Path Length
▽	2	0,60mm (23,62mil)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	r210_110h60_160r100m215_115				1,60mm (62,99mil)	1,00mm (39,37mil)
☆	2	0,60mm (23,62mil)	PTH	Slot	Top Layer - Bottom Layer	Pad	Rounded	r260_110h60_210r100m265_115				2,10mm (82,68mil)	1,50mm (59,06mil)
□	2	0,90mm (35,43mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c0hn90m95				-	-
⊕	32	1,10mm (43,31mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)				-	-
○	88	1,00mm (39,37mil)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	(Mixed)				-	-
✕	485	0,30mm (11,81mil)	PTH	Round	Top Layer - Bottom Layer	Via	Rounded	v80h30m0mx0				-	-
	611 Total												

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				⚡
	Top Solder	Solder Resist	0,018mm	4,2	
1	Top Layer	Copper	0,041mm		⚡
	Dielectric 1	FR-4	1,473mm	4,4	
2	Bottom Layer	Copper	0,041mm		⚡
	Bottom Solder	Solder Resist	0,018mm	4,2	
	Bottom Overlay				⚡



Project: NUCLEO64-MiniBoard

Layer: **Drill Drawing**

Variant: NoUSB

Date: 17-OCT-2021

Gerber: **.DRL**

Ref: MB1801

Rev: A

